SNx4AHCT595 8-Bit Shift Registers With 3-State Output Registers

1 Features

- Inputs are TTL-Voltage Compatible
- 8-Bit Serial-In, Parallel-Out Shift
- Shift Register Has Direct Clear
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

2 Applications

- Network Switches
- Power Infrastructures
- PCs ans Notebooks
- LED Displays
- Servers

3 Description

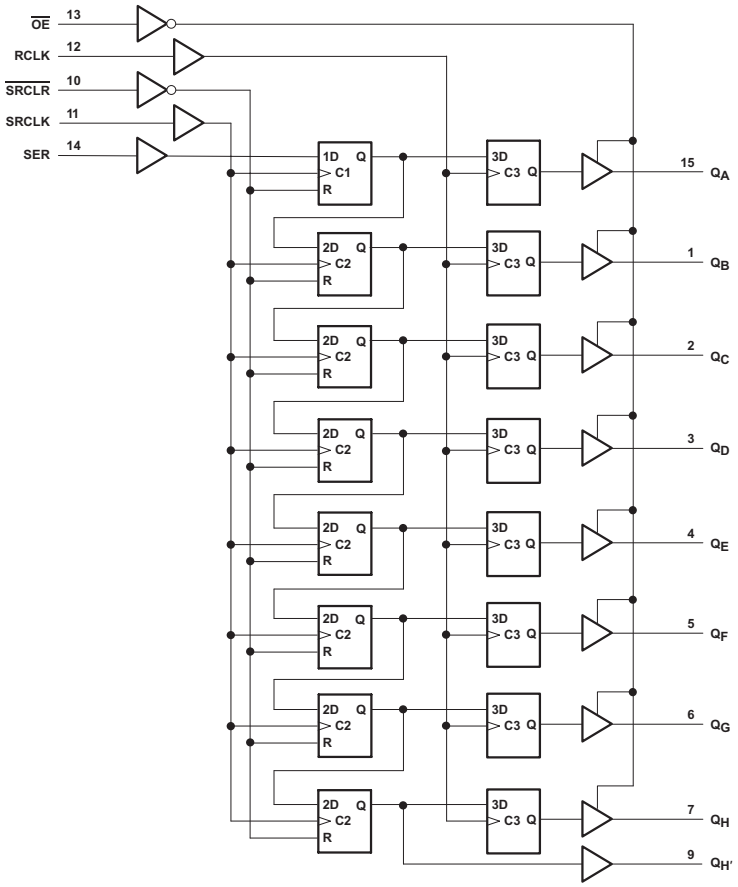
The SNx4AHCT595 devices contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. Both the shift register clock (SRCLK) and storage register clock (RCLK) are positive-edge triggered.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SNxAHCT595	PDIP (20)	24.33 mm 6.35 mm
	SOP (20)	12.60 mm x 5.30 mm
	SSOP (20)	7.50 mm x 5.30 mm
	TVSOP (20)	5.00 mm x 4.40 mm
	SOIC (20)	12.80 mm x 7.50 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

4 Simplified Schematic



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

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5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision M (July 2014) to Revision N — **Page**

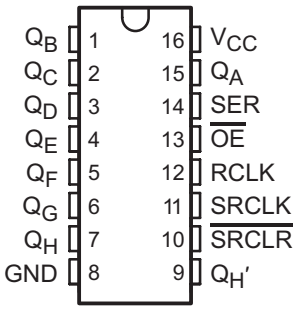
- Changed Pin Functions table. ... 3

Changes from Revision L (February 2004) to Revision M — **Page**

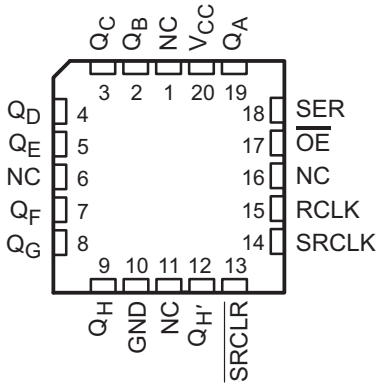
- Updated document to new TI data sheet format. ... 1
- Removed Ordering Information table. ... 1
- Added Applications. ... 1
- Changed MAX operating temperature from 85°C to 125°C in Recommended Operating Conditions table. ... 4
- Added Typical Characteristics. ... 7
- Added Detailed Description section. ... 9
- Added Application and Implementation section. ... 11

6 Pin Configuration and Functions

SN54AHCT595 . . . J OR W PACKAGE
SN74AHCT595 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AHCT595 . . . FK PACKAGE
(TOP VIEW)



NC − No internal connection

Pin Functions

PIN				I/O	DESCRIPTION
NAME	SN74AHCT595	SN54AHCT595			
	D, DB, DGV, N, NS, PW	J, W	FK		
GND	8	8	10	—	Ground Pin
$\overline{OE}$	13	13	17	I	Output Enable
Q_A	15	15	19	O	Q_A Output
Q_B	1	1	2	O	Q_B Output
Q_C	2	2	3	O	Q_C Output
Q_D	3	3	4	O	Q_D Output
Q_E	4	4	5	O	Q_E Output
Q_F	5	5	7	O	Q_F Output
Q_G	6	6	8	O	Q_G Output
Q_H	7	7	9	O	Q_H Output
$Q_{H'}$	9	9	12	O	$Q_{H'}$ Output
RCLK	12	12	14	I	RCLK Input
SER	14	14	18	I	SER Input
SRCLK	11	11	14	I	SRCLK Input
$\overline{SRCLR}$	10	10	13	I	$\overline{SRCLR}$ Input
NC		—	1	—	No Connection
			6		
			11		
			16		
V_{CC}	16	16	20	—	Power Pin

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	7	V
V_I	Input voltage range(2)		–0.5	7	V
V_O	Output voltage range(2)		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	V_I < 0		–20	mA
I_{OK}	Output clamp current	V_O < 0 or V_O > V_{CC}		±20	mA
I_O	Continuous output current	V_O = 0 to V_{CC}		±25	mA
	Continuous current through V_{CC} or GND			±50	mA

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

7.2 Handling Ratings

			MIN	MAX	UNIT
T_{stg}	Storage temperature range		–65	150	°C
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1)	0	2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2)	0	1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)(1)

		SN54AHCT595(2)		SN74AHCT595		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	5.5	0	5.5	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–8		–8	mA
I_{OL}	Low-level output current		8		8	mA
$\Delta t/\Delta v$	Input transition rise and fall time		20		20	ns/V
T_A	Operating free-air temperature	–55	125	–40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
(2) Product Preview

7.4 Thermal Information

THERMAL METRIC[1]		SN74AHCT595					UNIT
		D	DB	N	NS	PW	
		16 PINS					
$R_{\theta JA}$	Junction-to-ambient thermal resistance	80.2	97.5	47.5	79.1	105.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	39.1	47.7	34.9	35.4	40.4	
$R_{\theta JB}$	Junction-to-board thermal resistance	27.7	48.1	27.5	39.9	50.7	
ψ_{JT}	Junction-to-top characterization parameter	9.9	9.8	19.8	5.4	3.7	
ψ_{JB}	Junction-to-board characterization parameter	37.4	47.6	27.4	39.5	50.1	
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	n/a	n/a	n/a	n/a	n/a	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, SPRA953.

7.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C			SN54AHCT595[1]		SN74AHCT595		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 mA		4.5 V	4.4	4.5		4.4		4.4		V
	I_{OH} = –8 mA			3.94			3.8		3.8		
V_{OL}	I_{OL} = 50 µA		4.5 V			0.1		0.1		0.1	V
	I_{OL} = 8 mA					0.36		0.44		0.44	
I_I	V_I = 5.5 V or GND		0 to 5.5 V			±0.1		±1[2]		±1	µA
I_{OZ}	$V_O = V_{CC}$ or GND	$Q_A – Q_H$	5.5 V			±0.25		±2.5		±2.5	µA
I_{CC}	$V_I = V_{CC}$ or GND	I_O = 0	5.5 V			4		40		40	µA
ΔI_{CC}[3]	One input at 3.4V, Other inputs at V_{CC} or GND		5.5 V			2		2.2		2.2	mA
C_i	$V_I = V_{CC}$ or GND		5 V		3	10				10	pF
C_o	$V_O = V_{CC}$ or GND		5 V		5.5						pF

(1) Product Preview
(2) On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.
(3) This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

7.6 Timing Requirements

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 3)

PARAMETER			T_A = 25°C		SN54AHCT595[1]		SN74AHCT595		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	SRCLK high or low	5		5.5		5.5		ns
		RCLK high or low	5		5.5		5.5		
		$\overline{SRCLR}$ low	5		5		5		
t_{su}	Setup time	SER before SRCLK↑	3		3		3		ns
		SRCLK↑ before RCLK↑[2]	5		5		5		
		$\overline{SRCLR}$ low before RCLK↑	5		5		5		
		$\overline{SRCLR}$ high (inactive) before SRCLK↑	3.4		3.8		3.8		
t_h	Hold time	SER after SRCLK↑	2		2		2		ns

(1) Product Preview
(2) This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

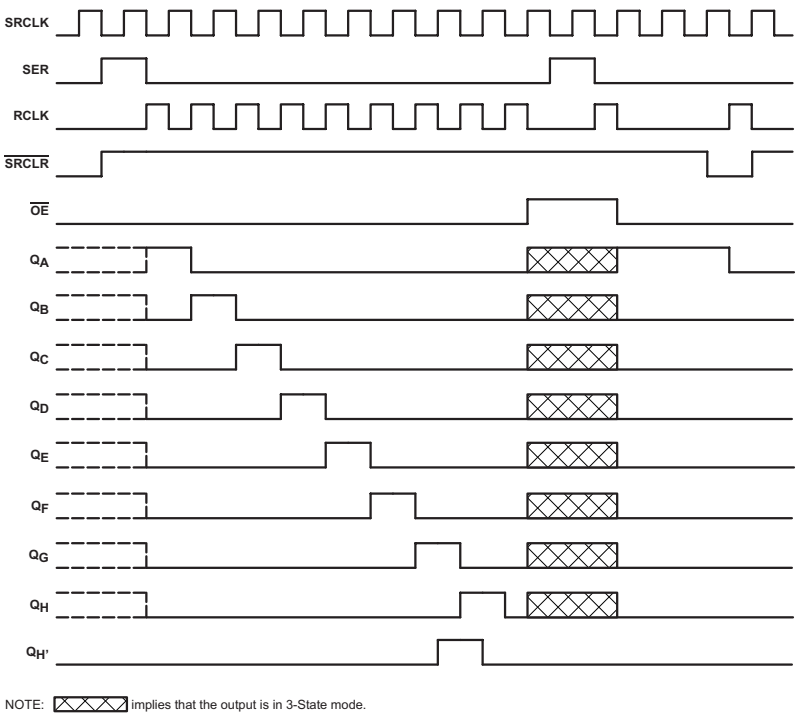


Figure 1. Timing Diagram

7.7 Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54AHCT595(1)		SN74AHCT595		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			C_L = 15 pF	135(2)	170(2)		115(2)		115		MHz
			C_L = 50 pF	95	140		85		85		
t_{PLH}	RCLK	Q_A – Q_H	C_L = 15 pF		4.3(2)	7.4(2)	1(2)	8.5(2)	1	8.5	ns
t_{PHL}					4.3(2)	7.4(2)	1(2)	8.5(2)	1	8.5	
t_{PLH}	SRCLK	$Q_{H'}$	C_L = 15 pF		4.5(2)	8.2(2)	1(2)	9.4(2)	1	9.4	ns
t_{PHL}					4.5(2)	8.2(2)	1(2)	9.4(2)	1	9.4	
t_{PHL}	$\overline{SRCLR}$	$Q_{H'}$	C_L = 15 pF		4.5(2)	8(2)	1(2)	9.1(2)	1	9.1	ns
t_{PZH}	$\overline{OE}$	Q_A – Q_H	C_L = 15 pF		4.3(2)	8.6(2)	1(2)	10(2)	1	10	ns
t_{PZL}					5.4(2)	8.6(2)	1(2)	10(2)	1	10	
t_{PLH}	RCLK	Q_A – Q_H	C_L = 50 pF		5.6	9.4	1	10.5	1	10.5	ns
t_{PHL}					5.6	9.4	1	10.5	1	10.5	
t_{PLH}	SRCLK	$Q_{H'}$	C_L = 50 pF		6.4	10.2	1	11.4	1	11.4	ns
t_{PHL}					6.4	10.2	1	11.4	1	11.4	
t_{PHL}	$\overline{SRCLR}$	$Q_{H'}$	C_L = 50 pF		6.4	10	1	11.1	1	11.1	ns
t_{PZH}	$\overline{OE}$	Q_A – Q_H	C_L = 50 pF		5.7	10.6	1	12	1	12	ns
t_{PZL}					6.8	10.6	1	12	1	12	
t_{PHZ}	$\overline{OE}$	Q_A – Q_H	C_L = 50 pF		3.5	10.3	1	11	1	11	ns
t_{PLZ}					3.4	10.3	1	11	1	11	

(1) Product Preview
(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.

7.8 Noise Characteristics(1)

V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C

PARAMETER		SN74AHCT595			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		1		V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		–0.6		V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		3.8		V
$V_{IH(D)}$	High-level dynamic input voltage	2			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.8	V

(1) Characteristics are for surface-mount packages only.

7.9 Operating Characteristics

V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	No load,	f = 1 MHz	112	pF

7.10 Typical Characteristics

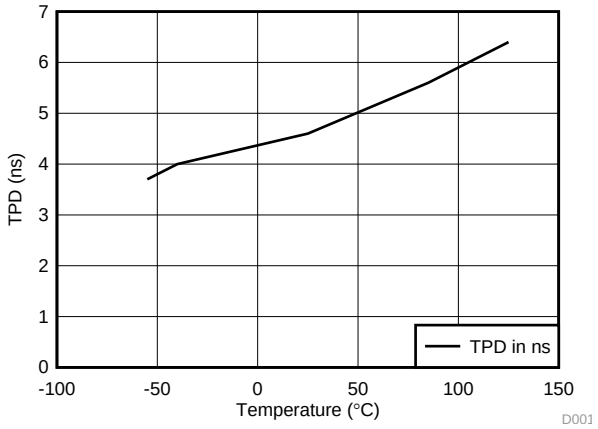
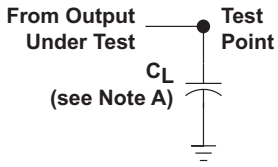
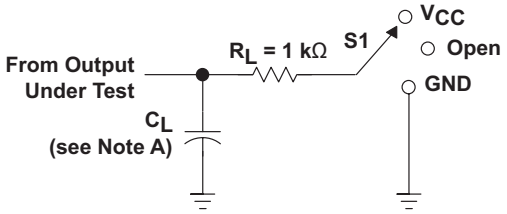


Figure 2. SN74AHCT595 TPD vs Temperature, 15 pF Load RCLK to Q

8 Parameter Measurement Information

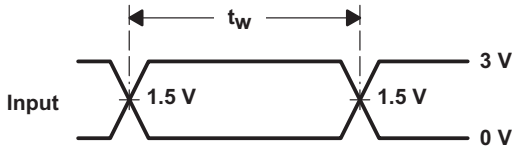


LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

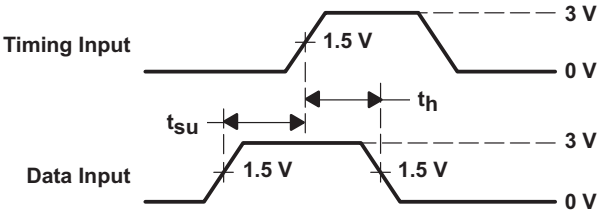


LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS

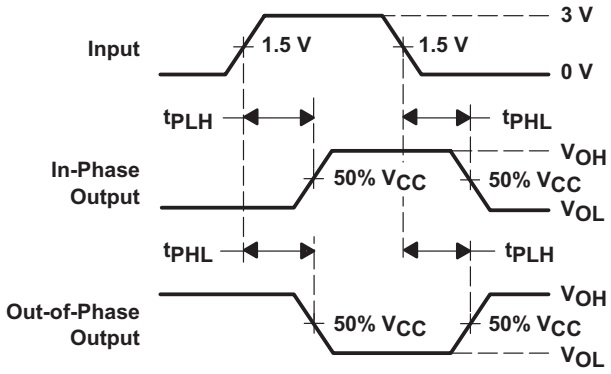
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}



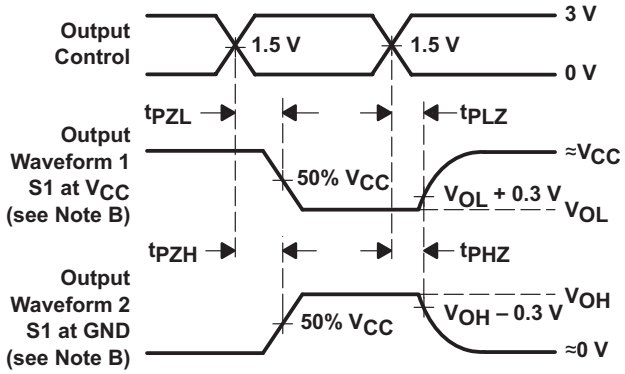
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
D. The outputs are measured one at a time, with one input transition per measurement.
E. All parameters and waveforms are not applicable to all devices.

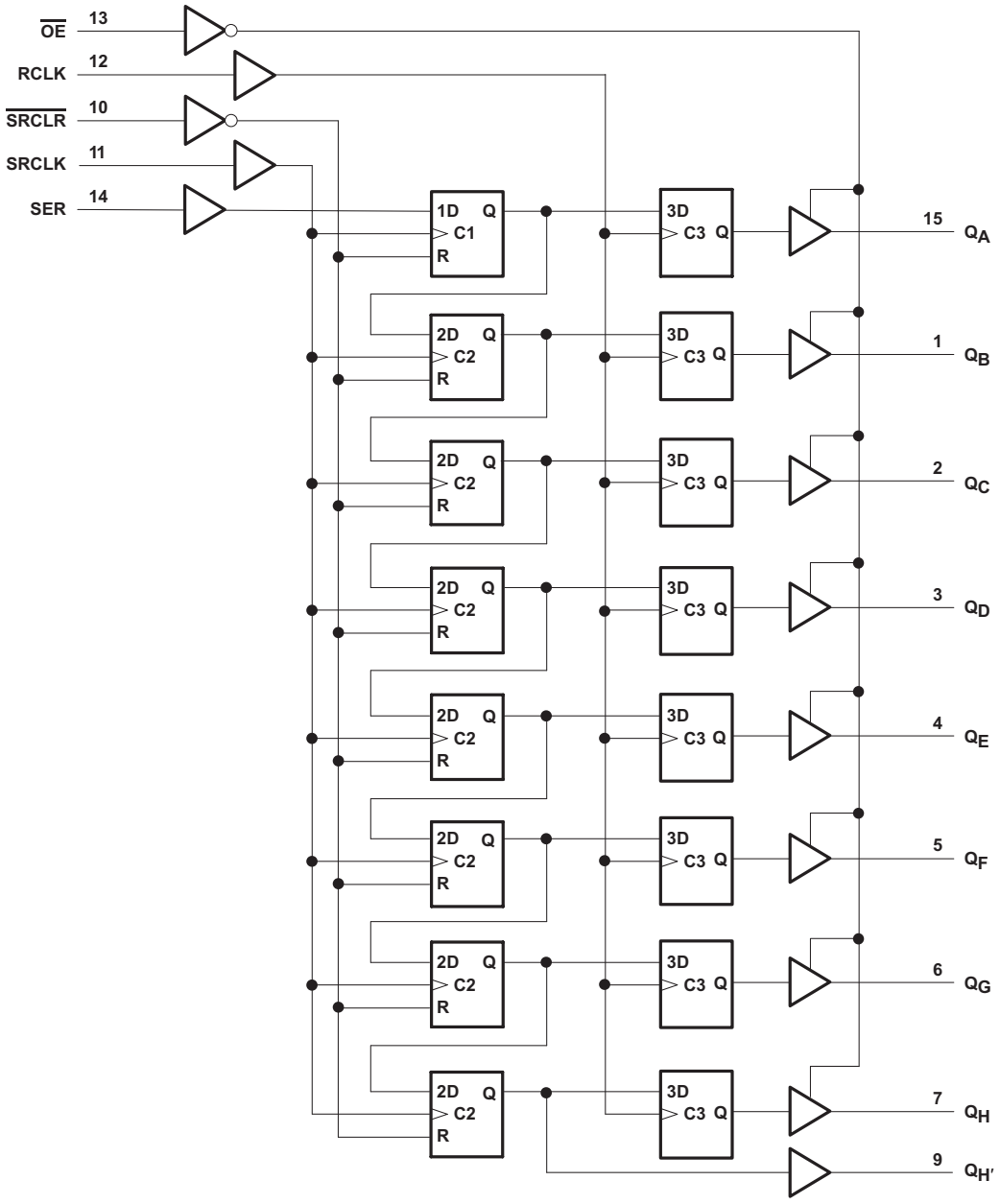
Figure 3. Load Circuit and Voltage Waveforms

9 Detailed Description

9.1 Overview

The SNx4AHCT595 devices contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. The storage register has parallel 3-state outputs. Separate clocks are provided for the shift and storage registers. The shift register has a direct overriding clear ($\overline{SRCLR}$) input, serial (SER) input, and serial outputs for cascading. When the output-enable ($\overline{OE}$) input is high, the outputs are in the high-impedance state. Both the shift register clock (SRCLK) and storage register clock (RCLK) are positive-edge triggered. If both clocks are connected together, the shift register always is one clock pulse ahead of the storage register.

9.2 Functional Block Diagram



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

9.3 Feature Description

- Inputs are TTL-voltage compatible
- Slow edges for reduced noise
- Low power

9.4 Device Functional Modes

Table 1. Function Table

INPUTS					FUNCTION
SER	SRCLK	$\overline{\text{SRCLR}}$	RCLK	$\overline{\text{OE}}$	
X	X	X	X	H	Outputs Q_A – Q_H are disabled.
X	X	X	X	L	Outputs Q_A – Q_H are enabled.
X	X	L	X	X	Shift register is cleared.
L	↑	H	X	X	First stage of the shift register goes low. Other stages store the data of previous stage, respectively.
H	↑	H	X	X	First stage of the shift register goes high. Other stages store the data of previous stage, respectively.
X	X	X	↑	X	Shift-register data is stored in the storage register.

10 Application and Implementation

10.1 Application Information

The SNx4AHCT595 is a low-drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The input switching levels have been lowered to accommodate TTL inputs of 0.8-V V_{IL} and 2-V V_{IH}. This feature makes it ideal for translating up from 3.3 V to 5 V. Figure 4 shows this type of translation.

10.2 Typical Application

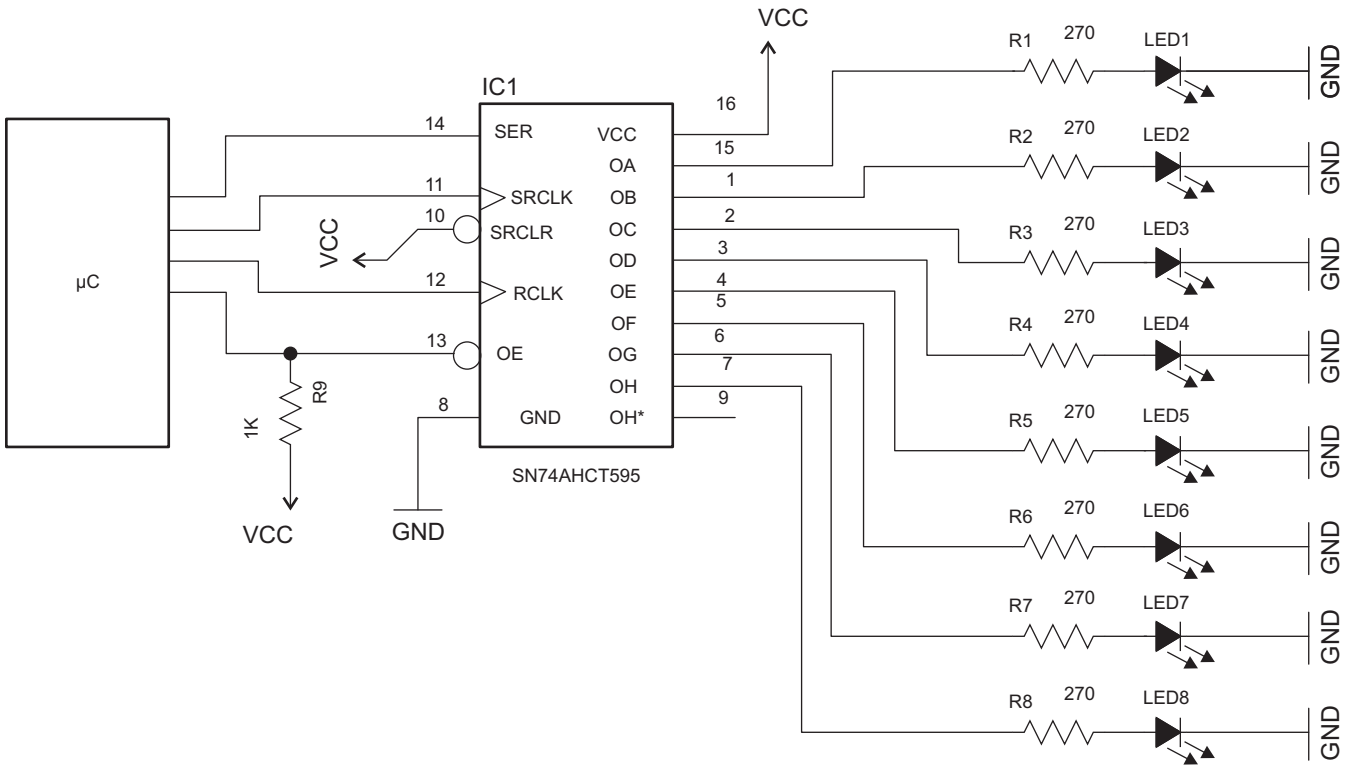


Figure 4. Specific Application Schematic

10.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so routing and load conditions should be considered to prevent ringing.

10.2.2 Detailed Design Procedure

- Recommended input conditions
  - Specified high and low levels. See (V_{IH} and V_{IL}) in the *Recommended Operating Conditions* table.
  - Specified high and low levels. See (V_{IH} and V_{IL}) in the *Recommended Operating Conditions* table.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC}
- Recommend output conditions
  - Load currents should not exceed 25 mA per output and 50 mA total for the part
  - Outputs should not be pulled above V_{CC}

Typical Application (continued)

10.2.3 Application Curves

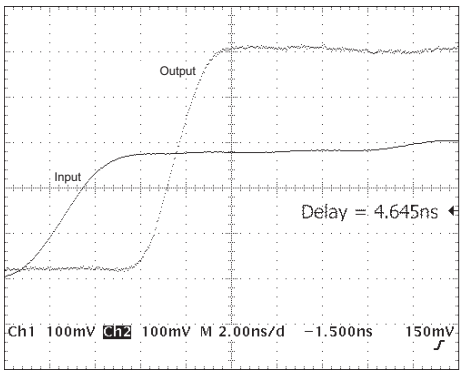


Figure 5. Typical Application Curve

11 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the *Recommended Operating Conditions* table.

Each VCC pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1 µf is recommended; if there are multiple VCC pins, then 0.01 µf or 0.022 µf is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1 µf and a 1 µf are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

12 Layout

12.1 Layout Guidelines

When using multiple-bit logic devices, inputs should never float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Figure 6 specifies the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC}, whichever makes more sense or is more convenient. It is generally acceptable to float outputs, unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the output section of the part when asserted. This will not disable the input section of the I/Os, so they cannot float when disabled.

12.2 Layout Example

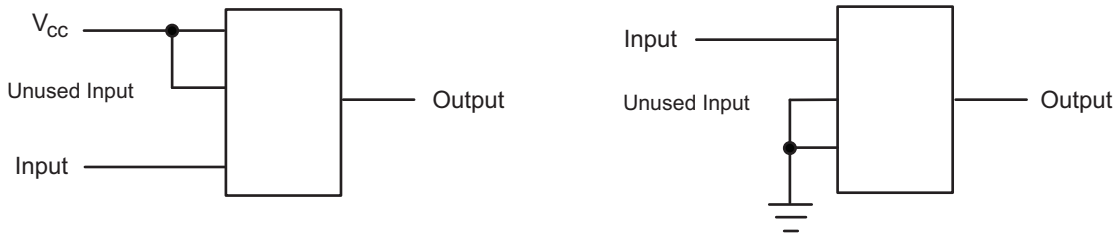


Figure 6. Layout Diagram

13 Device and Documentation Support

13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 2. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54AHCT595	Click here	Click here	Click here	Click here	Click here
SN74AHCT595	Click here	Click here	Click here	Click here	Click here

13.2 Trademarks

All trademarks are the property of their respective owners.

13.3 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

13.4 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AHCT595D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT595	Samples
SN74AHCT595DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB595	Samples
SN74AHCT595DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT595	Samples
SN74AHCT595DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT595	Samples
SN74AHCT595N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74AHCT595N	Samples
SN74AHCT595NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74AHCT595N	Samples
SN74AHCT595PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB595	Samples
SN74AHCT595PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB595	Samples
SN74AHCT595PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB595	Samples
SN74AHCT595PWRG3	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	HB595	Samples
SN74AHCT595PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB595	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

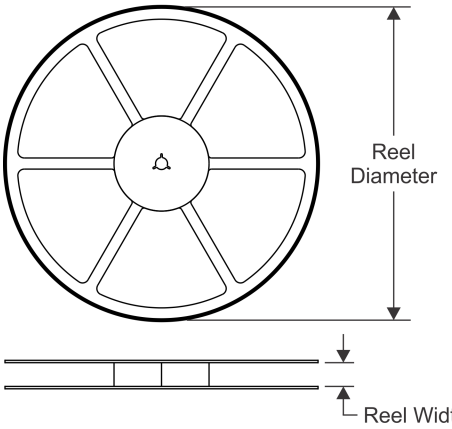
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

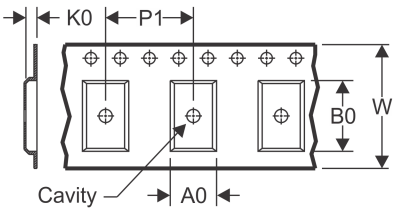
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

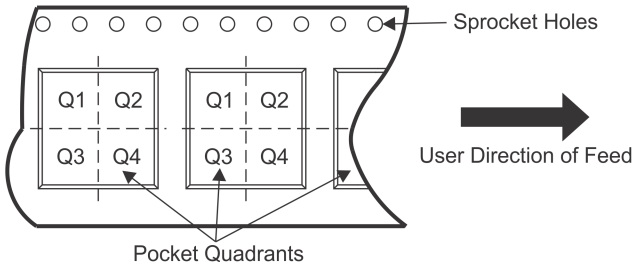


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

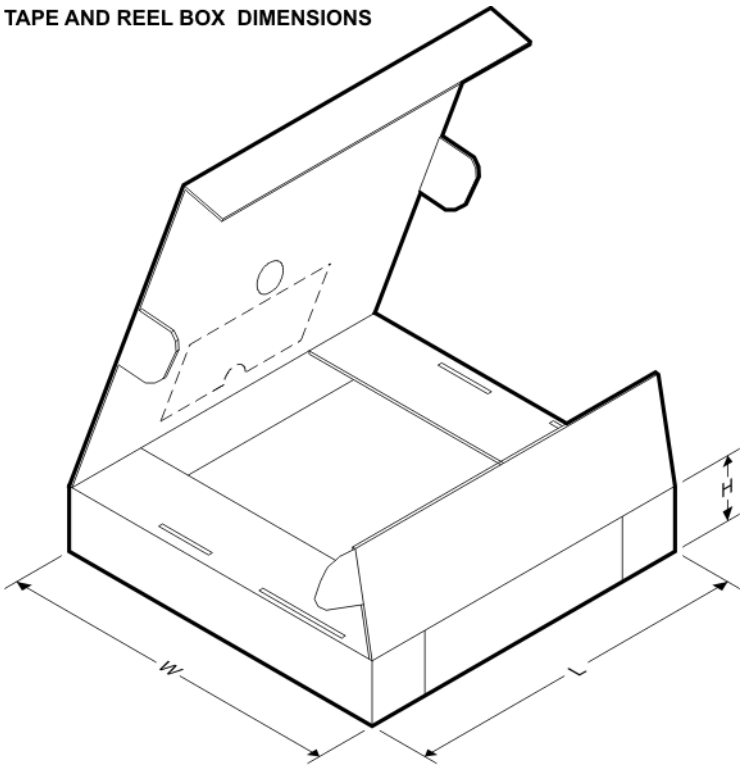
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT595DBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74AHCT595DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AHCT595PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT595PWRG3	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

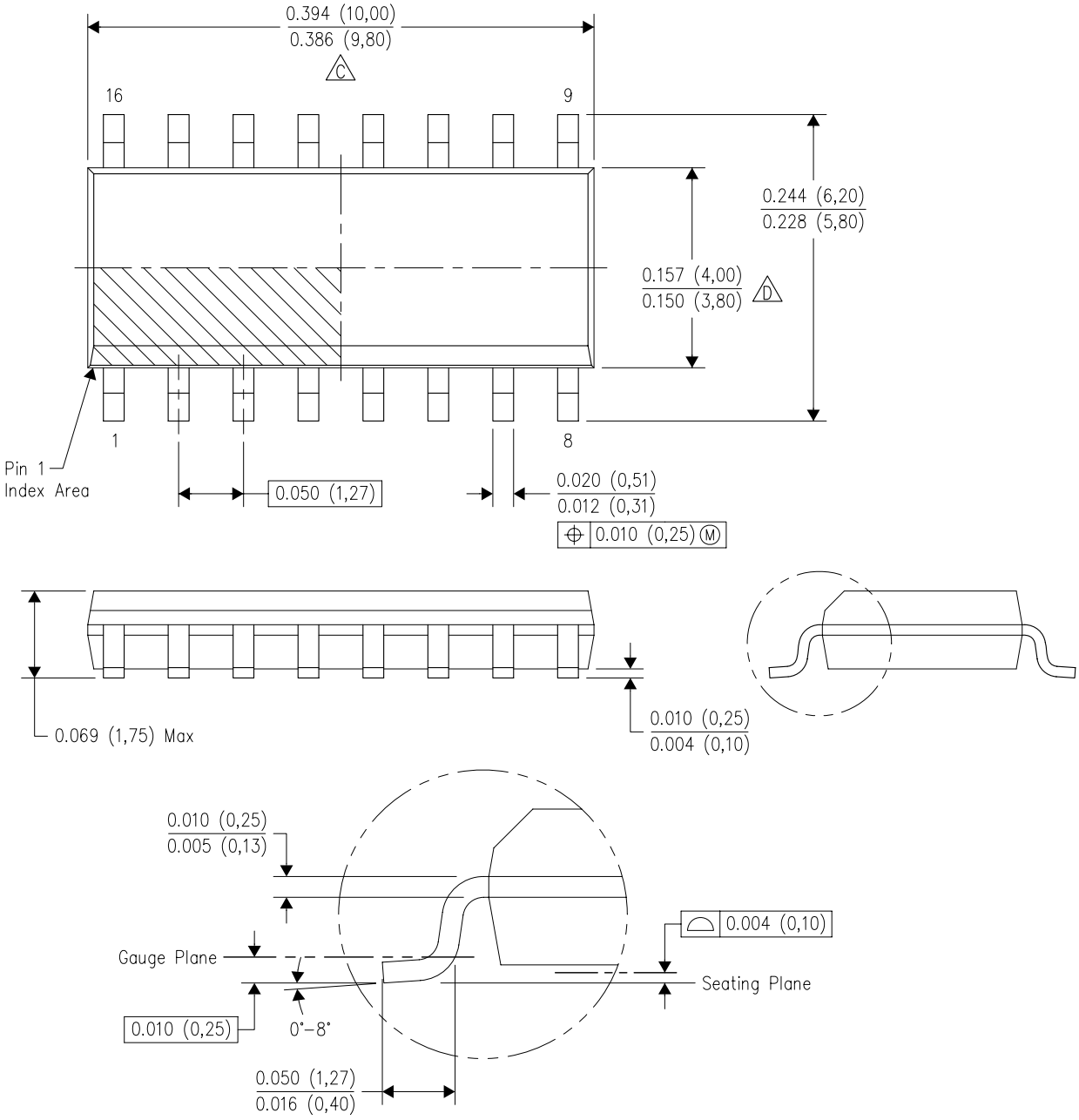
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

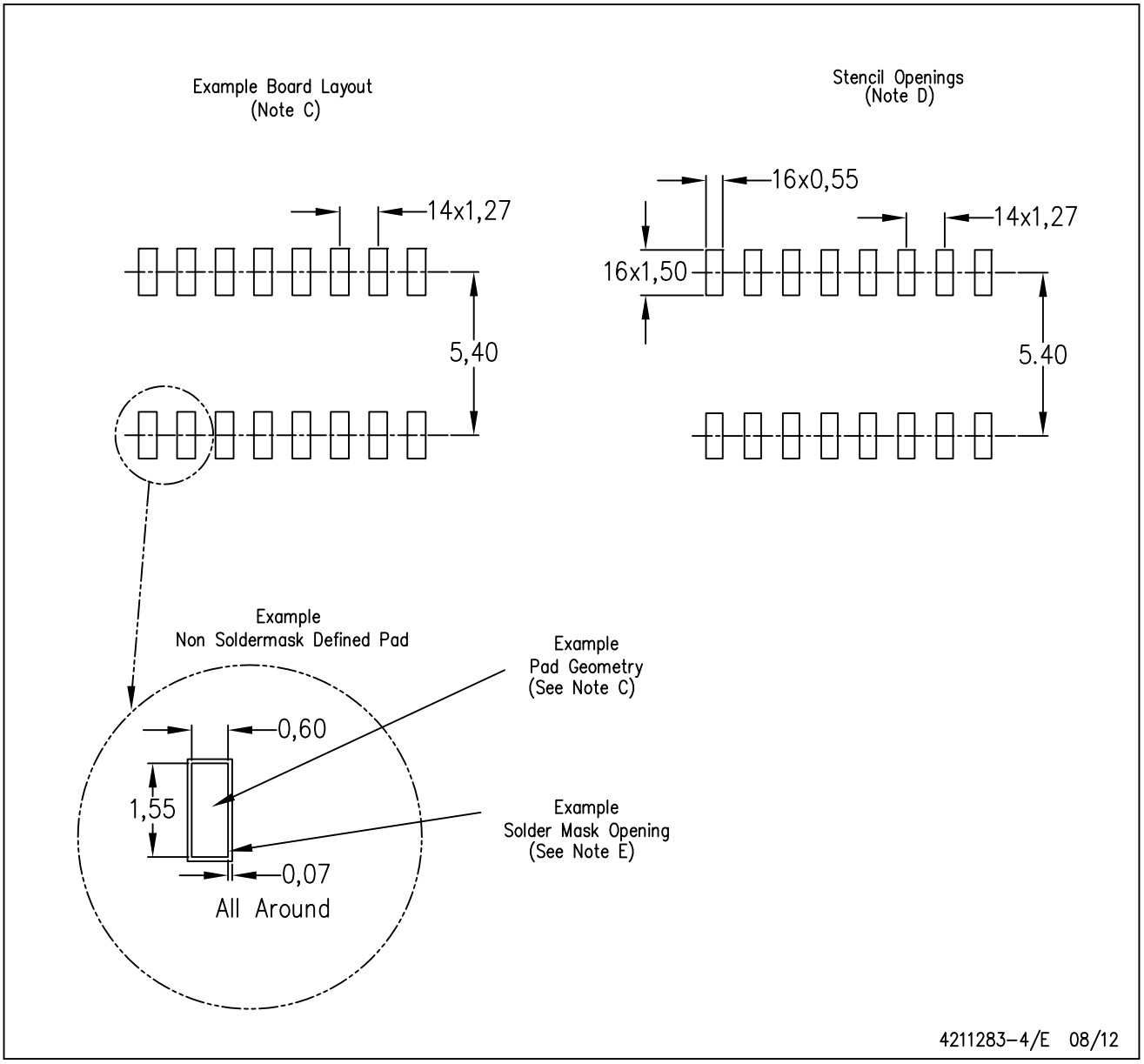
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT595DBR	SSOP	DB	16	2000	367.0	367.0	38.0
SN74AHCT595DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74AHCT595PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74AHCT595PWRG3	TSSOP	PW	16	2000	364.0	364.0	27.0

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



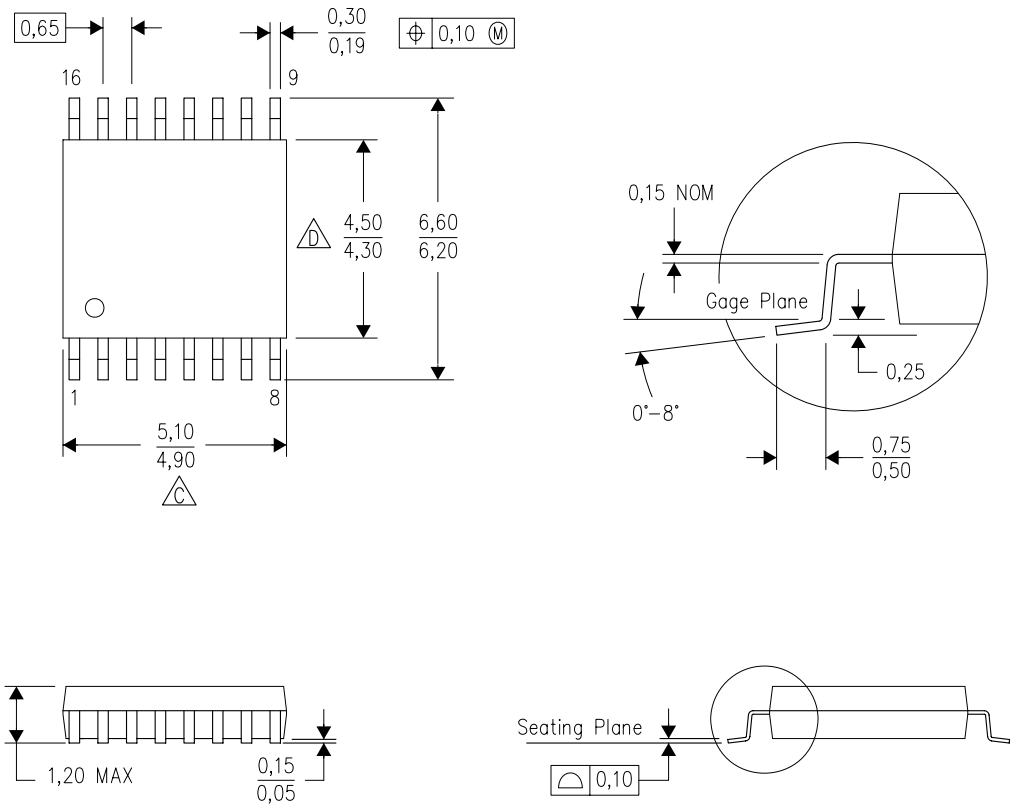
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

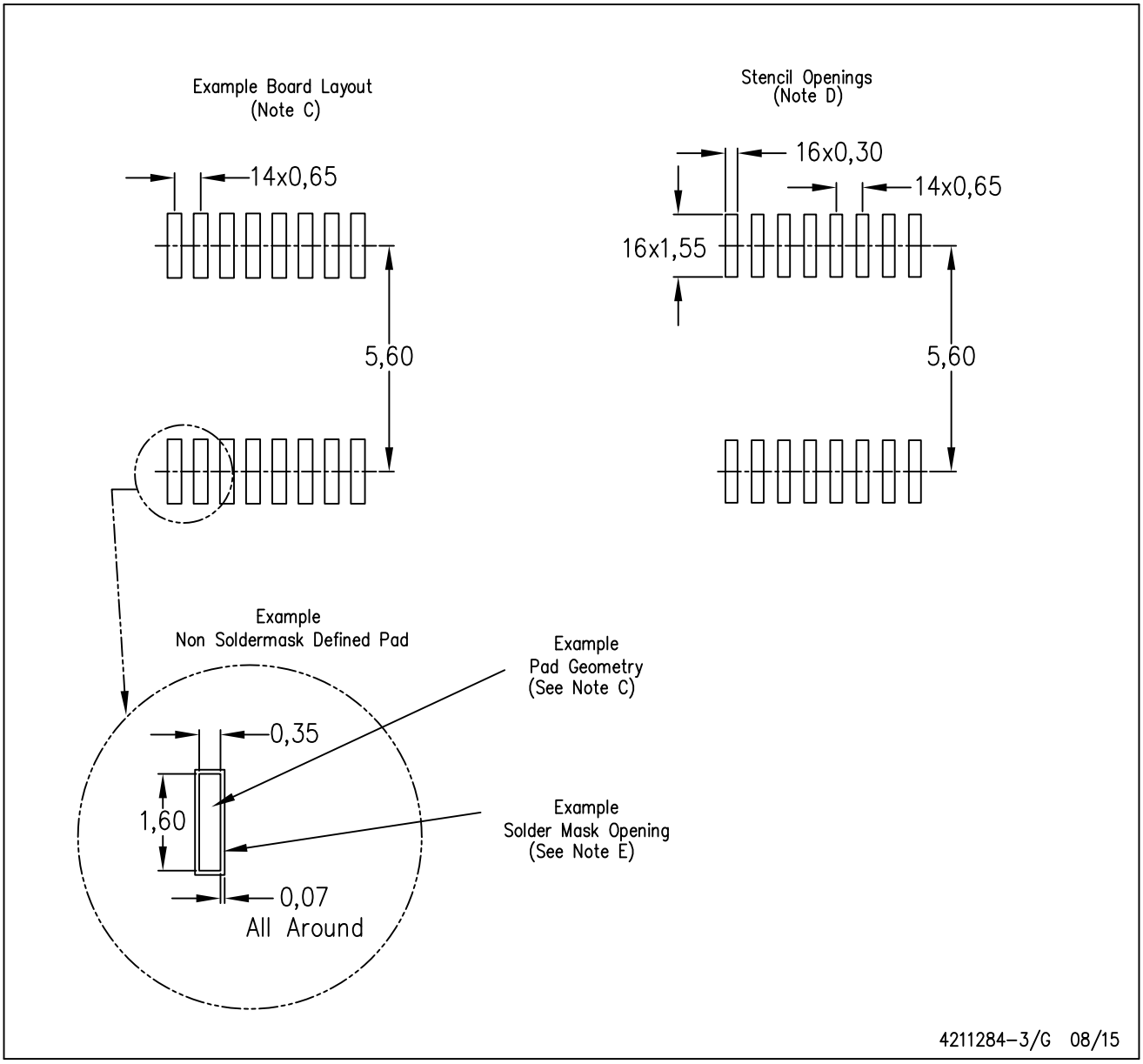
PW (R–PDSO–G16) PLASTIC SMALL OUTLINE



4040064–4/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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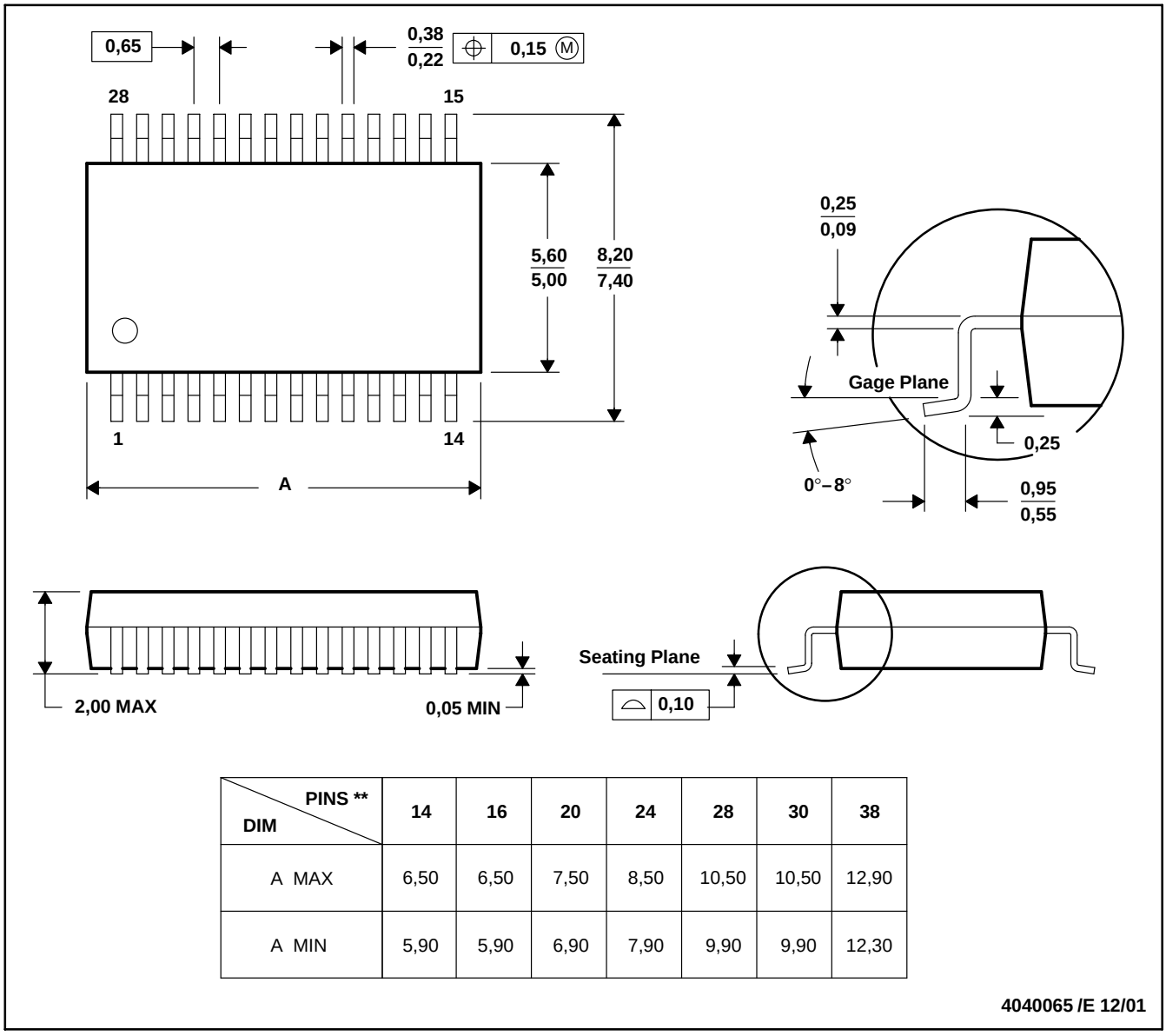
DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

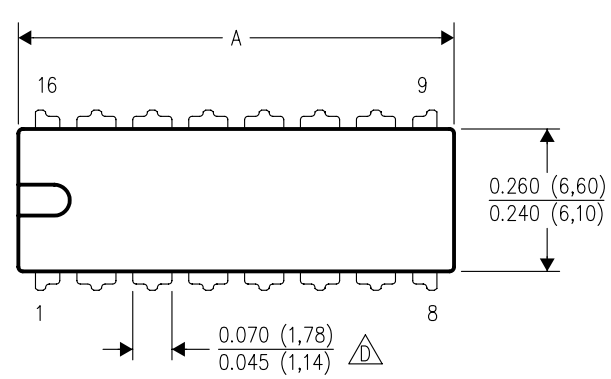
4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

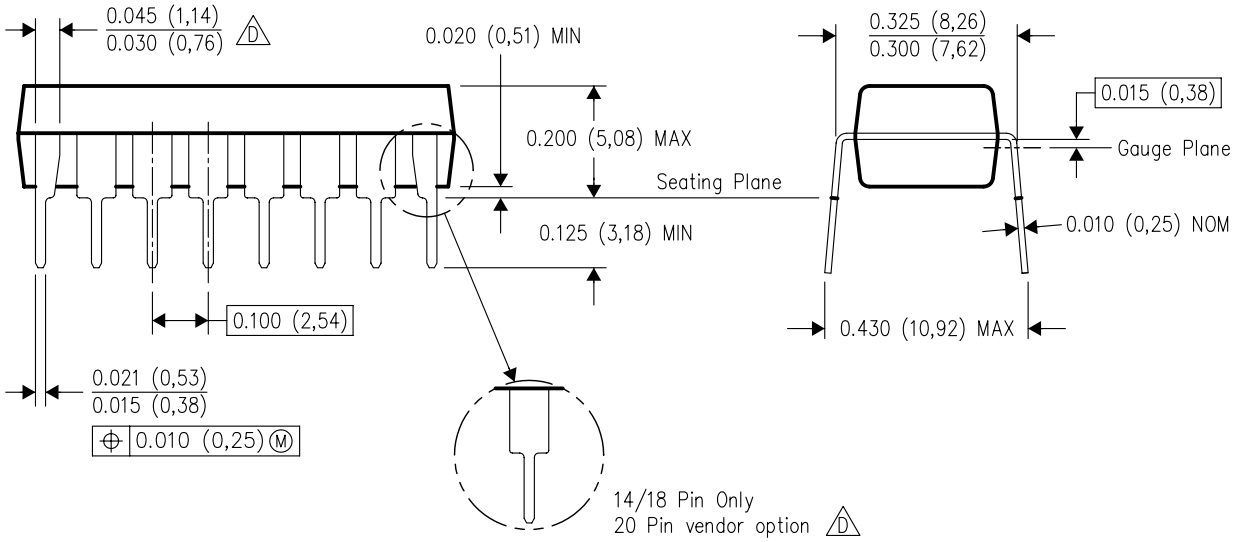
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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